

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (currently amended) Machine for cutting an opening, such as a window in a planar substrate, said machine having at least a cutting tool, a transfer system holding said substrate and driving transporting said substrate along a determined transport direction, and an aspiration box to maintain the substrate during the cutting operation, said cutting tool comprising a laser generating a laser beam that can be moved in two perpendicular directions and evacuation means to evacuate a cut part of said substrate, wherein said aspiration box is located on the same side of the substrate as said cutting tool and further comprises a bottom wall with aspiration openings to draw and hold against which said substrate ~~is aspirated against the bottom wall of the aspiration box by suction~~ and a cutting opening through which said laser beam is directed onto the substrate.

2. (currently amended) Machine according to claim 1, wherein said evacuation means evacuate the cut part by aspiration sucking the cut part through said cutting opening provided in the bottom wall of the aspiration box.

3. (currently amended) Machine according to claim 1, wherein said evacuation means comprise an evacuation outlet for evacuating the cut part by aspiration sucking the cut part through the evacuation outlet which is disposed on the other side of the substrate with respect to the surface against which the substrate is applied during the cutting operation.

4. (previously presented) Machine according to claim 3, wherein said cutting opening is closed by a transparent material, such as glass.

5. (previously presented) Machine according to claim 1, wherein said transfer system is a chain gripper system comprising a chain on which gripper bars are mounted.

6. (previously presented) Machine according to claim 1, wherein said laser is displaced linearly or rotationally.

7. (previously presented) Machine according to claim 1, wherein said laser beam is displaced linearly or rotationally.

8. (previously presented) Machine according to claim 1, further comprising a laminate application unit for applying a strip of laminate over the cut opening of the substrate.

9. (currently amended) Process for cutting an opening, such as a window, in a planar substrate, said process being characterized by the following steps:

- holding said substrate with a gripper,
- ~~moving~~ transporting said substrate by means of the gripper along a given transport direction,
- applying drawing said substrate against an aspiration surface by ~~using air under~~ depression suction to hold said substrate against said aspiration surface,
- directing a laser beam onto said substrate through a cutting opening provided in said aspiration surface to cut an opening in said substrate thereby creating a cut part,
- evacuating the cut part of said substrate during the step of drawing said substrate against an aspiration surface.

10. (currently amended) Process according to claim 9, wherein said cut part is evacuated by ~~aspiration~~ sucking the cut part through said cutting opening provided in the aspiration surface.

11. (currently amended) Process according to claim 9, wherein said cut part is evacuated by ~~aspiration~~ sucking the cut part through an evacuation outlet disposed on the other side of the substrate with respect to the aspiration surface against which the substrate is applied during the cutting operation.

12. (previously presented) Process according to claim 9, wherein said laser is displaced linearly or rotationally.

13. (previously presented) Process according to claim 9, wherein said laser beam is displaced linearly or rotationally.

14. (previously presented) Process according to claim 13, wherein a mirror displaces said laser beam.

15. (previously presented) Process according to claim 9, further comprising the step of applying laminate over the cut opening of the substrate.